

- Solutions for Your µ tasks
- 18 years of expertise
- >400 feasibility studies a year





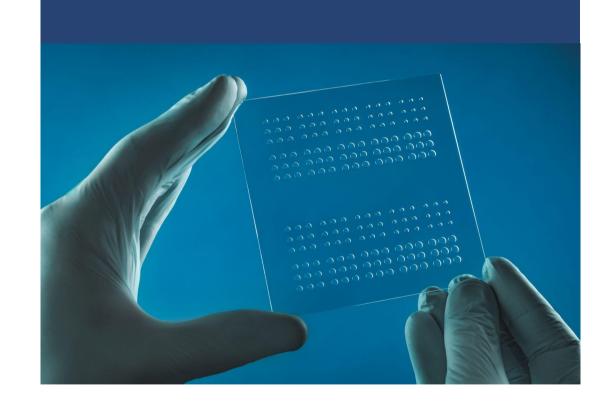
Full-Service Solution

HAVE A MICRON CHALLENGE?

Need to work it out?

PROTOTYPING

We will investigate your task and deliver a prototype to test it in real environment.



Need to scale?

PRODUCTION SERVICES

We will deliver small to medium scale production services from 1 unit.



Need a tool?

LASER SYSTEM DEVELOPMENT

We will develop a laser system for your specific application and transfer with the recipe.



All materials: glass, sapphire, ceramics, metal, plastic, optical fibers...



Glass Dicing

WOP technology outperforms

other glass-cutting methods

	Blade dicing	Stealth laser dicing	WOP laser dicing
Glass thickness	2 – 19 mm	200 μm – 10 mm	30 μm – 2 mm
Glass type	All types	Non-tempered Sapphire	Tempered Non-tempered Sapphire
Cutting speed	Up to 100 mm/s	Up to 300 mm/s	Up to 1000 mm/s
Possible shapes	Straight cuts only	T-shape and round shapes possible	Any shape possible
Surface chipping	<200 μm	<50 μm	<10 µm



up to

1000 mm/s





Irregular shapes

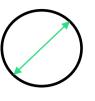




wophotonics.com

Glass Drilling

Hole diameter (from 20 μm



Hole size tolerance ± 1µm

Aspect ratio 1:100

1?

How many

10?

holes

100?

can you

1000?

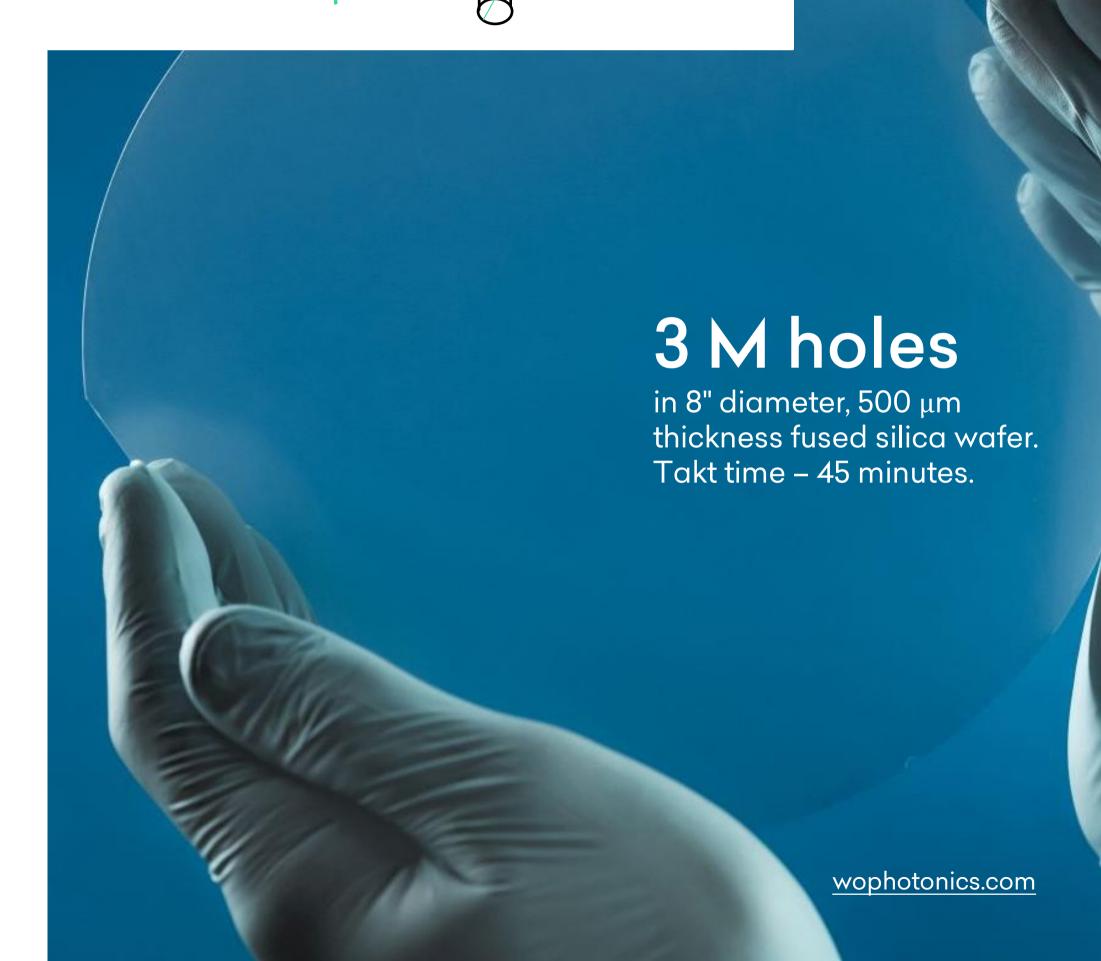
drill

in glass per

50 000+

WOP benchmark 1 minute?



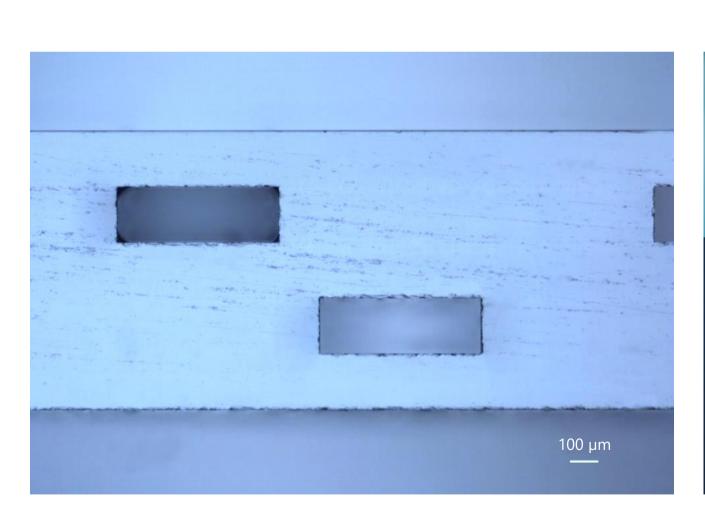


What's in it for You?

Clients' latest benefits in choosing WOP

Microfluidic chip bonding:

• 5 hermetic layers bonded without adhesive (side view)



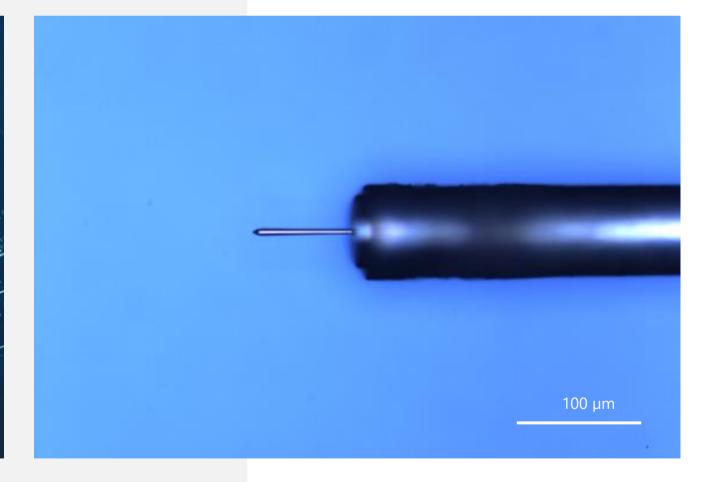
Switch ceramics to glass for probe cards:

- 80% less defects
- 20x faster processing



Metal needle micromachining for biomedical R&D project:

• tip diameter ≥ 5 μm







Don't hesitate, contact us!

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Our Clients



































